
IN THE CLAIMS

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1. (Amended) A chemical vapor deposition (CVD) process for depositing borophosphosilicate glass films on a substrate surface, the process comprising:
 - disposing the substrate within a chemical vapor deposition reaction chamber;
 - heating the substrate to a temperature within a range of at least 480°C to about 700°C;
 - introducing a gas volume of SiO₂ precursors into the chamber;
 - admitting a gas volume of ozone into the chamber;
 - admitting a dopant source for phosphorus into the chamber;
 - admitting a dopant source for boron into the chamber; and
 - exposing a reaction volume of gases located above the substrate surface within a chemically reactive distance of the substrate to a high intensity light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and
 - subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the borophosphosilicate glass film layer.
 2. (Amended) The process method of Claim 1, wherein the SiO₂ precursor is selected from the group consisting of TEOS (tetraethylorthosilicate), TMCTS (tetramethylcyclotetrasiloxane), DES (diethylsilane), DTBS (ditertiarybutylsilane), TMOS (tetramethylorthosilicate) and FTES (fluorotriethoxysilane).
 3. (Previously Canceled)
 4. (Amended) The process method of Claim 1, wherein the dopant source for boron is selected from the group consisting of triisopropylborate, TMB (trimethylborate), and TEB (triethylborate), and the dopant source for phosphorus is selected from the group

consisting of TEPO (triethylphosphate), TEPi (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite).

5. (Amended) The process method of Claim 1, further comprising introducing a gas volume of a carrier gas into the reaction chamber.

I 6. (Amended) The process method of Claim 5, wherein the dopant source for boron is selected from the group consisting of triisopropylborate, TMB (trimethylborate) and TEB (triethylborate), and the dopant source for phosphorus is selected from the group consisting of TEPO (triethylphosphate), TEPi (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite).

7-30. (Previously Canceled)

31. (Amended) A method of depositing a silicon dioxide layer on a substrate surface, the method comprising:

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor and ozone;

heating the substrate surface to a temperature of at least 480°C to about 700°C; and

illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than in homogeneous reactions taking place in the chamber outside of the reaction volume[[],]; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

32. (Previously Canceled)

33. (Previously Added) The method of Claim 31, wherein the reaction volume of gas further comprises a carrier gas.

34. (Previously Added) The method of Claim 31, wherein the reaction volume of gas further comprises a carrier gas selected from the group consisting of the Noble gases, nitrogen and hydrogen.

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35. (Previously Added) The method of Claim 31, wherein the reaction volume of gas further comprises a carrier gas comprising helium.

36. (Previously Added) The method of Claim 31, wherein ozone comprises approximately 5% to 15% by volume of the reaction volume of gas.

37. (Previously Canceled)

38. (Previously Added) The method of Claim 31, further comprising:
subjecting the reaction volume of gas to a pressure of approximately 200 torr during deposition of the silicon dioxide layer.

39. (Previously Added) The method of Claim 31, wherein the SiO₂ precursor is selected from the group consisting of TEOS (tetraethylorthosilicate), TMCTS (tetramethylcyclotetrasiloxane), DES (diethylsilane), DTBS (ditertiarybutylsilane), TMOS (tetramethylorthosilicate) and FTES (fluorotriethoxysilane).

40. (Previously Added) The method of Claim 31, wherein the reaction volume of gas further comprises at least one dopant source selected from the group consisting of triisopropylborate, TMB (trimethylborate), TEB (triethylborate), TEPO

(triethylphosphate), TEPI (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite).

I 41. (Previously Added) The method of Claim 31, wherein the reaction volume of gas further comprises at least one dopant source for boron selected from the group consisting of triisopropylborate, TMB (trimethylborate), and TEB (triethylborate), and at least one dopant source for phosphorus selected from the group consisting of TEPO (triethylphosphate), TEPI (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite).

42. (Amended) A method of depositing a doped silicon dioxide layer on a substrate surface, the method comprising:

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor, ozone and at least one dopant source;

heating the substrate surface to a temperature of at least 480°C to about 700°C; and

illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

43. (Amended) A method of depositing a doped silicon dioxide layer on a substrate surface, comprising:

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor, ozone and at least two dopant sources;

heating the substrate surface to a temperature of at least 480°C to about 700°C; and

I illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

44. (Previously Added) The method of Claim 43, wherein the at least two dopant sources comprise a dopant source for boron and a dopant source for phosphorus.

45. (Amended) A method of depositing a borophosphosilicate glass layer on a substrate surface, comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, wherein the reaction volume of gas comprises:

a SiO₂ precursor selected from the group consisting of TEOS (tetraethylorthosilicate), TMCTS (tetramethylcyclotetrasiloxane), DES (diethylsilane), DTBS (ditertiarybutylsilane) and TMOS (tetramethylorthosilicate);

a dopant source for boron selected from the group consisting of triisopropylborate, TMB (trimethylborate), and TEB (triethylborate); and

a dopant source for phosphorus selected from the group consisting of TEPO (triethylphosphate), TEPi (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite);

illuminating the reaction volume of gas from a high intensity light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, ~~the~~ reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

46. (Amended) A method of depositing a fluorosilicate glass layer on a substrate surface, comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a fluorinated SiO₂ precursor and ozone; and

illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, ~~the~~ reactant gases in the reaction volume take part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the fluorosilicate layer.

47. (Amended) A method of depositing a doped fluorosilicate glass layer on a substrate surface, the method comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a fluorinated SiO₂ precursor, ozone and at least one dopant source; and

I illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

48. (Amended) A method of depositing a doped fluorosilicate glass layer on a substrate surface, the method comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a fluorinated SiO₂ precursor, ozone and at least two dopant sources; and

illuminating the reaction volume of gas from a high-intensity light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the fluorosilicate layer.

49. (Previously Added) The method of Claim 48, wherein the at least two dopant sources comprise a dopant source for boron and a dopant source for phosphorus.

50. (Amended) A method of depositing a fluoroborophosphosilicate glass layer on a substrate surface, the method comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, wherein the reaction volume of gas comprises:

a SiO₂ precursor comprising FTES (fluorotriethoxysilane);

a dopant source for boron selected from the group consisting of triisopropylborate, TMB (trimethylborate), and TEB (triethylborate); and

a dopant source for phosphorus selected from the group consisting of TEPO (triethylphosphate), TEPi (triethylphosphite), TMPo (trimethylphosphate) and TMPi (trimethylphosphite); and

illuminating the reaction volume of gas from a high intensity light source without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the fluoroborophosphosilicate layer.

51. (Amended) A method of depositing a silicon dioxide layer on a substrate surface, the method comprising:

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor and ozone;

heating the substrate surface to a temperature of at least 480°C to about 700°C; and

I illuminating the reaction volume of gas from a light source comprising mercury arc vapor lamps without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

52. (Amended) A method of depositing a doped silicon dioxide layer on a substrate surface, the method comprising:

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor, ozone and at least one dopant source;

heating the substrate surface to a temperature of at least 480°C to about 700°C; and

illuminating the reaction volume of gas from a light source comprising mercury arc vapor lamps without directly exposing the substrate surface to the light source to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

53. (Amended) A method of depositing a doped silicon dioxide layer on a substrate surface, the method comprising:

heating the substrate surface to a temperature of at least 480°C to about 700°C;

contacting the substrate surface with a reaction volume of gas located above the substrate surface within a chemically reactive distance of the substrate, the reaction volume of gas comprising a SiO₂ precursor, ozone and at least two dopant sources; and

illuminating the reaction volume of gas from a light source without directly exposing the substrate surface to the light source, the light source comprising mercury arc vapor lamps to increase the functional atomic oxygen concentration and reduce the fixed charge in the deposited films, the reactant gases in the reaction volume taking part in heterogeneous chemical reactions, rather than homogeneous reactions taking place in the chamber outside of the reaction volume; and

subjecting the reaction volume of gas to a pressure of approximately 200 to 760 torr during deposition of the silicon dioxide layer.

54. (Previously Added) The method of Claim 53, wherein the at least two dopant sources comprise a dopant source for boron and a dopant source for phosphorus.
